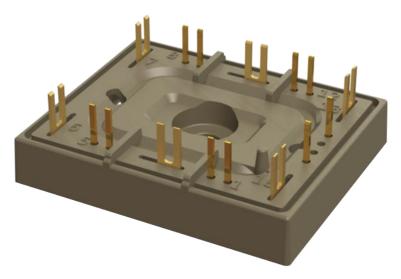
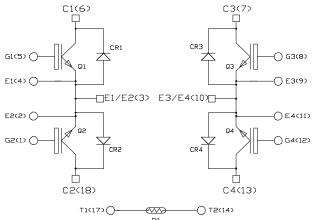
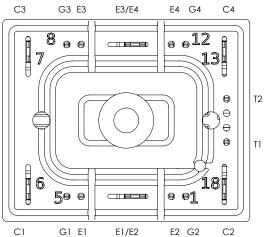
# Double Dual Common Emitter High-Speed IGBT4 Power Module

#### **Product Overview**

The MSCGLQ50DDU120CTBL2NG device is a 1200 V, 50 A double dual common emitter high-speed IGBT4 power module.







All ratings at  $T_J = 25$ °C, unless otherwise specified.

Caution: These devices are sensitive to electrostatic discharge. Proper handling procedures must be followed.

#### **Features**

The following are the key features of MSCGLQ50DDU120CTBL2NG device:

- · High speed IGBT4
  - Low voltage drop
  - Low leakage current
  - Low switching losses
- · SiC Schottky Diode
  - Zero reverse recovery
  - Zero forward recovery
  - Temperature independent switching behavior
  - Positive temperature coefficient on VF
- · Ultra low weight and profile
- Kelvin emitter for easy drive
- Si<sub>3</sub>N<sub>4</sub> substrate with thick copper for improved thermal performance
- Internal thermistor for temperature monitoring
- Extended temperature range

#### **Benefits**

The following are the benefits of MSCGLQ50DDU120CTBL2NG device:

- High efficiency converter
- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction-to-heatsink thermal resistance
- Low profile
- RoHS Compliant
- Solderable terminals both for power and signal for easy PCB mounting
- Very integrated power conversion system

## **Application**

The following are the applications of MSCGLQ50DDU120CTBL2NG device:

- · High reliability power systems
- AC switches

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## 1. Electrical Specifications

This section provides the electrical specifications of MSCGLQ50DDU120CTBL2NG device.

#### 1.1 IGBT4 Characteristics (Per IGBT)

The following table lists the absolute maximum ratings of MSCGLQ50DDU120CTBL2NG device.

**Table 1-1. Absolute Maximum Ratings** 

| Symbol           | Parameter  | Parameter I            |     | Unit |
|------------------|--|------------------------|-----|------|
| V <sub>CES</sub> | Collector-Emitter voltage                                    | or-Emitter voltage     |     | V    |
| I <sub>C</sub>   | I <sub>C</sub> Continuous collector current T <sub>H</sub> = |                        | 110 | Α    |
|                  |  | T <sub>H</sub> = 100°C | 50  |      |
| I <sub>CM</sub>  | Pulsed collector current                                     | T <sub>H</sub> = 25°C  | 180 |      |
| V <sub>GE</sub>  | Gate-Emitter voltage   |                        | ±20 | V    |
| P <sub>D</sub>   | Power dissipation  | T <sub>H</sub> = 25 °C | 375 | W    |

The following table lists the electrical characteristics of MSCGLQ50DDU120CTBL2NG device.

**Table 1-2. Electrical Characteristics** 

| Symbol               | Characteristic                      | Test Conditions                                   |                        | Min | Тур  | Max | Unit |
|----------------------|-------------------------------------|---|------------------------|-----|------|-----|------|
| I <sub>CES</sub>     | Zero gate voltage collector current | V <sub>GE</sub> = 0 V<br>V <sub>CE</sub> = 1200 V |                        | _   | _    | 25  | μΑ   |
| V <sub>CE(sat)</sub> | Collector emitter                   | V <sub>GE</sub> = 15 V                            | T <sub>J</sub> = 25°C  | 1.7 | 2.05 | 2.4 | V    |
|                      | saturation voltage                  | I <sub>C</sub> = 50 A                             | T <sub>J</sub> = 150°C | _   | 2.6  | _   |      |
| $V_{GE(th)}$         | Gate threshold voltage              | $V_{GE} = V_{CE}$<br>$I_C = 1.7 \text{ mA}$       |                        | 5.3 | 5.8  | 6.3 | V    |
| I <sub>GES</sub>     | Gate-Emitter leakage current        | V <sub>GE</sub> = 20 V<br>V <sub>CE</sub> = 0 V   |                        | _   | _    | 150 | nA   |

**Electrical Specifications** 

The following table lists the dynamic characteristics of MSCGLQ50DDU120CTBL2NG device.

#### **Table 1-3. Dynamic Characteristics**

| Symbol              | Characteristic                    | Test Condition   | ons                          |                        | Min | Тур  | Max | Unit |
|---------------------|-----------------------------------|--|------------------------------|------------------------|-----|------|-----|------|
| C <sub>ies</sub>    | Input capacitance                 | V <sub>GE</sub> = 0 V  |                              |                        | _   | 2770 | _   | pF   |
| C <sub>oes</sub>    | Output capacitance                | V <sub>CE</sub> = 25 V   |                              |                        |     | 185  | _   |      |
| C <sub>res</sub>    | Reverse transfer capacitance      | f = 1 MHz  |                              |                        | _   | 160  | _   |      |
| Q <sub>g</sub>      | Total gate charge                 | V <sub>GE</sub> = 15 V<br>V <sub>CE</sub> = 960 V<br>I <sub>C</sub> = 50 A     | V <sub>CE</sub> = 960 V      |                        | _   | 230  | _   | nC   |
| T <sub>d(on)</sub>  | Turn-on delay time                | V <sub>GE</sub> = ±15 V  |                              | T <sub>J</sub> = 150°C | _   | 30   | _   | ns   |
| T <sub>r</sub>      | Rise time                         | V <sub>Bus</sub> = 600 V   |                              |                        | _   | 49   | _   |      |
| T <sub>d(off)</sub> | Turn-off delay time               | I <sub>C</sub> = 50 A  |                              |                        | _   | 366  | _   |      |
| T <sub>f</sub>      | Fall time                         | $R_G = 10 \Omega$  |                              |                        |     | 48   | _   |      |
| E <sub>on</sub>     | Turn-on switching energy          | $V_{GE} = \pm 15 \text{ V}$ $V_{Bus} = 600 \text{ V}$                          |                              | T <sub>J</sub> = 150°C | _   | 2.8  | _   | mJ   |
| E <sub>off</sub>    | Turn-off switching energy         | $I_C = 50 \text{ A}$ $R_G = 10 \Omega$   |                              | T <sub>J</sub> = 150°C | _   | 2.8  | _   |      |
| $R_G$               | Integrated gate resiste           | or   |                              |                        | _   | 4    | _   | Ω    |
| I <sub>SC</sub>     | Short circuit data                | $V_{GE} \le 15 \text{ V}$ $V_{Bus} = 900 \text{ V}$ $t_p \le 10  \mu \text{s}$ |                              | T <sub>j</sub> = 150°C | _   | 190  |     | A    |
| R <sub>thJH</sub>   | Junction-to-heatsink t resistance | hermal   | λ <sub>paste</sub> = 3.4 W/r | nK                     | _   | 0.4  | _   | °C/W |

#### 1.2 SiC Diode Ratings and Characteristics (Per SiC Diode)

The following table lists the SiC diode ratings and characteristics of MSCGLQ50DDU120CTBL2NG device.

Table 1-4. SiC Diode Ratings and Characteristics

| Symbol            | Characteristic                      | Test Condition          | ons |                         | Min | Тур   | Max  | Unit |
|-------------------|-------------------------------------|-------------------------|-----|-------------------------|-----|-------|------|------|
| V <sub>RRM</sub>  | Peak repetitive reverse             | voltage                 |     |                         | _   | _     | 1200 | V    |
| I <sub>RM</sub>   | Reverse leakage                     | V <sub>R</sub> = 1200 V |     | T <sub>J</sub> = 25 °C  | _   | 10    | 200  | μΑ   |
|                   | current                             |                         |     | T <sub>J</sub> = 175 °C | _   | 150   | _    |      |
| I <sub>F</sub>    | DC forward current                  | _                       |     | T <sub>H</sub> = 100 °C | _   | 30    | _    | А    |
| V <sub>F</sub>    | Diode forward voltage               | I <sub>F</sub> = 30 A   |     | T <sub>J</sub> = 25 °C  | _   | 1.5   | 1.8  | V    |
|                   |                                     |                         |     | T <sub>J</sub> = 175 °C | _   | 2.1   | _    |      |
| Q <sub>C</sub>    | Total capacitive charge             | V <sub>R</sub> = 600 V  |     |                         | _   | 130   | _    | nC   |
| С                 | Total capacitance                   | f = 1 MHz               |     | _                       | 141 |       | pF   |      |
|                   |                                     | V <sub>R</sub> = 400 V  |     |                         |     |       |      |      |
|                   |                                     | f = 1 MHz               |     |                         | _   | 105   | _    |      |
|                   |                                     | V <sub>R</sub> = 800 V  |     |                         |     |       |      |      |
| R <sub>thJH</sub> | Junction-to-heatsink the resistance | rmal                    | mal |                         | _   | 0.854 | _    | °C/W |

#### 1.3 Thermal and Package Characteristics

The following table lists the thermal and package characteristics of the MSCGLQ50DDU120CTBL2NG device.

Table 1-5. Thermal and Package Characteristics

| Symbol            | Characteristic   |             |     | Min         | Тур  | Max                   | Unit |
|-------------------|--|-------------|-----|-------------|------|-----------------------|------|
| V <sub>ISOL</sub> | RMS isolation voltage, any terminal to case t = 1 min, 50 Hz/60 Hz |             |     |             | _    | _                     | V    |
| T <sub>J</sub>    | Operating junction temperature r                                   | ange        |     | <b>-</b> 55 | _    | 175                   | °C   |
| T <sub>JOP</sub>  | Recommended junction temperature under switching conditions        |             |     | <b>-</b> 55 | _    | T <sub>Jmax</sub> –25 |      |
| T <sub>STG</sub>  | Storage case temperature   |             |     | <b>-</b> 55 | _    | 125                   |      |
| T <sub>C</sub>    | Operating case temperature   |             |     | <b>-</b> 55 | _    | 125                   |      |
| Torque            | Mounting torque  | To heatsink | 1.5 | _           | 2    | N.m                   |      |
| Wt                | Package weight   |             |     | _           | 21.5 | _                     | g    |

**Electrical Specifications** 

The following table lists the temperature sensor NTC of the MSCGLQ50DDU120CTBL2NG device.

Table 1-6. Temperature Sensor NTC

| Symbol                 | Characteristic             |                         | Min | Тур  | Max | Unit |
|------------------------|----------------------------|-------------------------|-----|------|-----|------|
| R <sub>25</sub>        | Resistance at 25 °C        |                         | _   | 50   | _   | kΩ   |
| $\Delta R_{25}/R_{25}$ |                            |                         | _   | 5    | _   | %    |
| B <sub>25/85</sub>     | T <sub>25</sub> = 298.15 K |                         | _   | 3952 | _   | K    |
| ΔΒ/Β                   | _                          | T <sub>C</sub> = 100 °C | _   | 4    | _   | %    |

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$
 T: Thermistor temperature R<sub>T</sub>: Thermistor value at T

Note: See APT0406—Using NTC Temperature Sensor Integrated into Power Module for more information.

#### 1.4 Typical IGBT 4 Performance Curve (Per IGBT)

This section shows the typical IGBT 4 performance curves of MSCGLQ50DDU120CTBL2NG device.

Figure 1-1. Junction-to-Heatsink Thermal Impedance

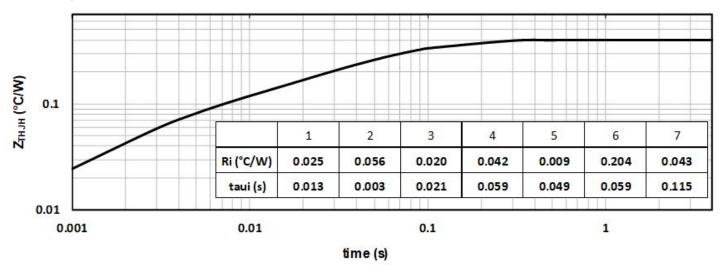


Figure 1-2. Output Characteristics (V<sub>GE</sub> = 15 V)

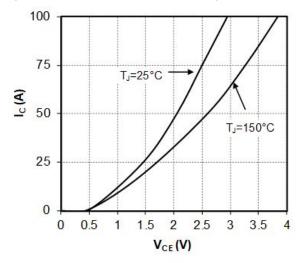


Figure 1-3. Output Characteristics

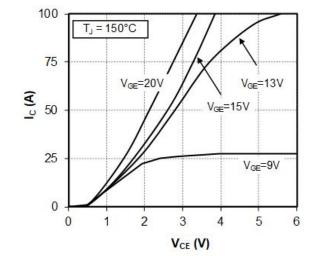


Figure 1-4. Transfer Characteristics

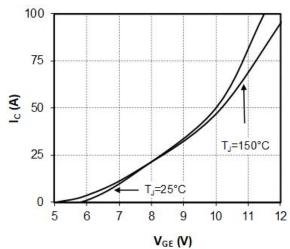


Figure 1-5. Energy Losses vs. Collector Current

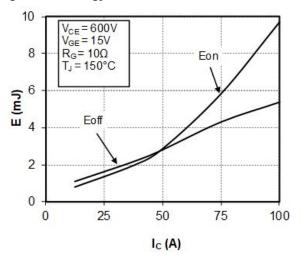


Figure 1-6. Switching Energy Losses vs. Gate Resistance

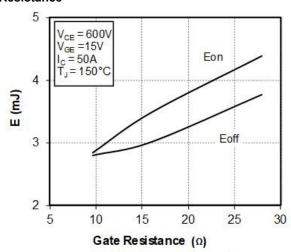
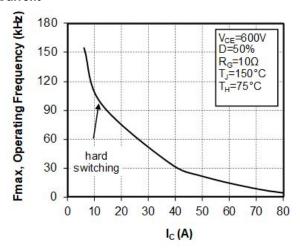


Figure 1-7. Operating Frequency vs. Collector Current



#### 1.5 Typical SiC Diode Performance Curves (Per SiC Diode)

This section shows the typical SiC diode performance curves of MSCGLQ50DDU120CTBL2NG device.

Figure 1-8. Junction-to-Heatsink Thermal Impedance

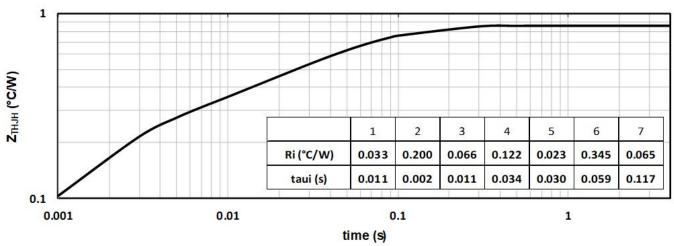


Figure 1-9. Forward Characteristics

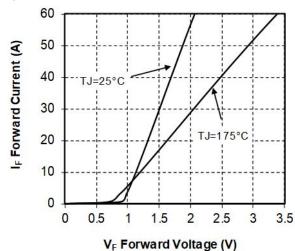
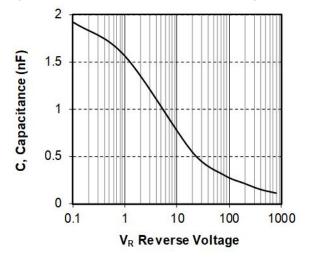


Figure 1-10. Capacitance vs. Reverse Voltage



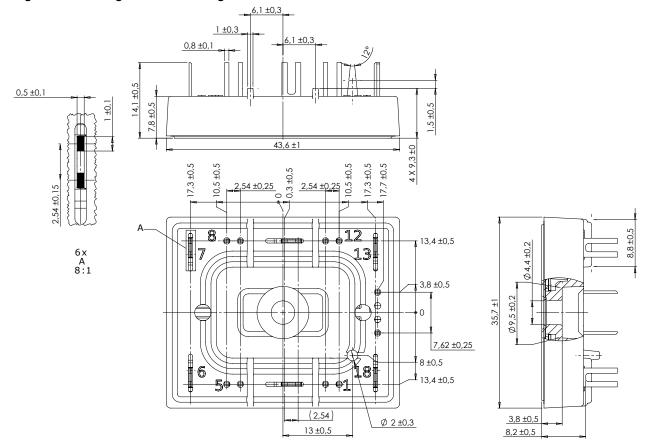
#### 2. Package Specifications

The following section shows the package specification of MSCGLQ50DDU120CTBL2NG device.

#### 2.1 Package Outline

The following figure shows the package outline drawing of MSCGLQ50DDU120CTBL2NG device. The dimensions in the following figure are in millimeters.

Figure 2-1. Package Outline Drawing



**Revision History** 

# 3. Revision History

| Revision | Date    | Description      |
|----------|---------|------------------|
| Α        | 07/2021 | Initial Revision |

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